

SOT2000-1

FM8, flange mount package, 8 terminals, 1.02 mm pitch, 10.26 mm x 10.26 mm x 3.81 mm body

28 October 2019

Package information

1 Package summary

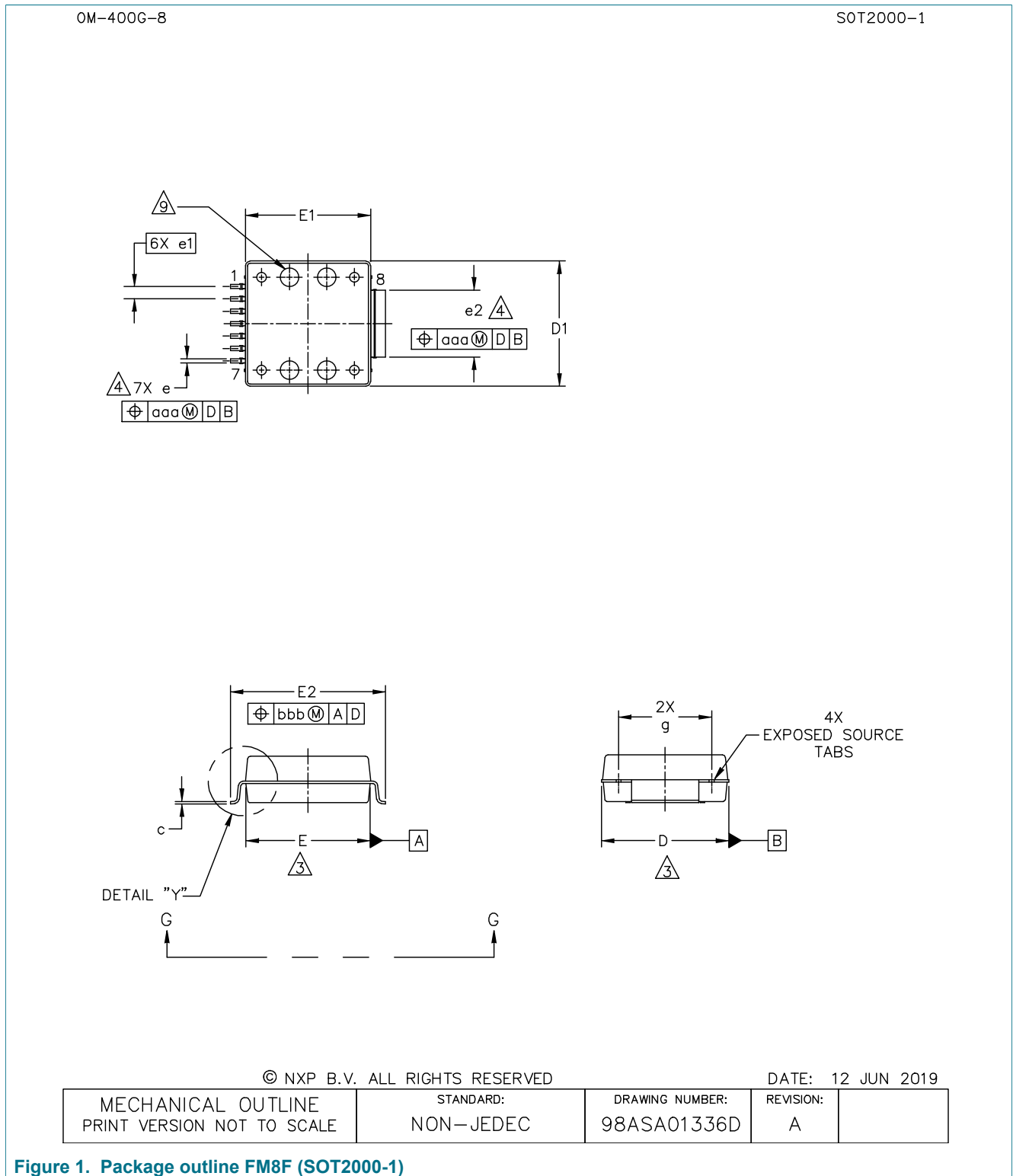
Terminal position code	S (single)
Package type descriptive code	FM8
Mounting method type	F (flange mount)
Issue date	12-06-2019
Manufacturer package code	98ASA01336D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	10.21	10.26	10.31	mm
package width	10.21	10.26	10.31	mm
seated height	3.73	3.81	3.89	mm
nominal pitch	-	1.02	-	mm
actual quantity of termination	-	8	-	



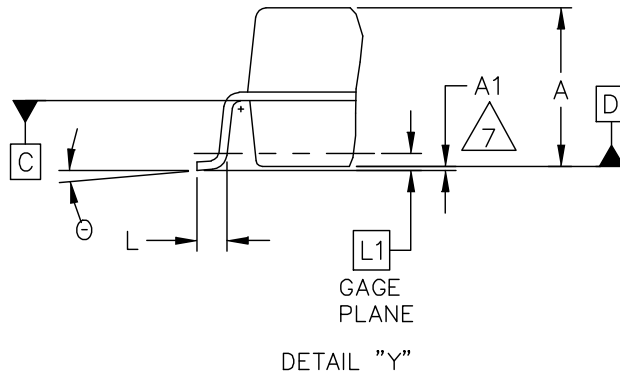
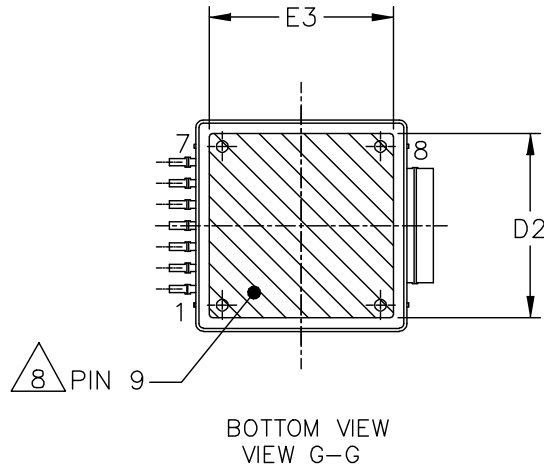
2 Package outline



FM8, flange mount package, 8 terminals, 1.02 mm pitch, 10.26 mm x 10.26 mm x 3.81 mm body

OM-400G-8

SOT2000-1



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DATE: 12 JUN 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JEDEC	DRAWING NUMBER: 98ASA01336D	REVISION: A	
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Figure 2. Package outline detail FM8F (SOT2000-1)

FM8, flange mount package, 8 terminals, 1.02 mm pitch, 10.26 mm x 10.26 mm x 3.81 mm body

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NOTES:

1. CONTROLLING DIMENSION: INCH
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M-1994.
3. DIMENSIONS D & E DOES NOT REFLECT PLASTIC OR METAL PROTRUSIONS OF PACKAGE PART LINE. ALLOWABLE PROTRUSION IS .006 INCH (0.15 MM).
4. DIMENSIONS e & e2, DO NOT INCLUDE DAMBAR PROTRUSIONS. ALLOWABLE PROTRUSIONS IS .005 INCH (0.13 MM).
5. DATUM PLANE C IS LOCATE AT THE BOTTOM OF THE LEAD AND IS COINCIDENT WITH THE LEAD WHERE THE LEAD EXITS THE PLASTIC BODY AT THE BOTTOM OF THE PARTING LINE.
6. DATUMS A AND B TO BE DETERMINED AT DATUM PLANE C.
7. DIMENSION A1 IS MEASURED WITH REFERENCE TO DATUM D. THE POSITIVE VALUE IMPLIES THAT THE BOTTOM OF THE PACKAGE IS HIGHER THAN THE BOTTOM OF THE LEAD.
8. HATCHING AREA REPRESENTS EXPOSED AREA OF THE HEATSINK. DIMENSIONS D1 AND E1 REPRESENT THE VALUES BETWEEN THE TWO OPPOSITE POINTS ALONG THE EDGES OF THE EXPOSED AREA OF HEAT SLUG.
9. DIMPLED HOLE REPRESENTS PIN 1.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	.147	.153	3.73	3.89	e	.011	.017	0.28	0.43
A1	.000	.005	0.00	0.13	e1	.040 BSC		1.02 BSC	
D	.398	.402	10.11	10.21	e2	.213	.219	5.41	5.56
D1	.402	.406	10.21	10.31	c	.007	.009	0.18	0.23
D2	.343	.353	8.71	8.97	g	.295	.305	7.49	7.75
E	.398	.402	10.11	10.21	θ	1°	9°	1°	9°
E1	.402	.406	10.21	10.31	aaa	.005		0.13	
E2	.495	.505	12.57	12.83	bbb	.010		0.25	
E3	.343	.353	8.71	8.97					
L	.026	.032	0.66	0.81					
L1	.010 BSC		0.25 BSC						

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Figure 3. Package outline note FM8F (SOT2000-1)

3 Legal information

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